# **OSRAM** LA G6SP.02 **Datasheet**





### Advanced Power TOPLED®

# LA G6SP.02 - Dual binning

The Advanced Power TOPLED.02 (APT.02) features ams OSRAM's state-of-the-art generation of PLCC 6 packages, which have set a market standard in the mid power LED world and were decades ago the first of its kind. With its very robust design, the APT.02 family can withstand harsh environmental conditions and offers the highest level of processability. Containing our latest InGaAIP-chip technology the APT.02 keeps its market leading brightness performance and offers a wide range of available bins with a high luminous efficiency and an excellent thermal resistance.





#### **Applications**

- Signalling

#### **Features**

- Package: white SMT package, colorless clear silicone resin
- Chip technology: Thinfilm
- Typ. Radiation: 120° (Lambertian emitter)
- Color: λ<sub>dom</sub> = 617 nm (• amber)
- Corrosion Robustness Class: 3B
- Qualifications: AEC-Q102 Qualified with RV-level 1
- ESD: 2 kV acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 2)





# **Ordering Information**

Туре	Luminous Intensity <sup>1)</sup> I <sub>F</sub> = 10 mA I <sub>v</sub>	Luminous Intensity <sup>1)</sup> I <sub>F</sub> = 140 mA I <sub>V</sub>	Ordering Code	
LA G6SP.02-U2AA-1-A3D3+7E6F-24-G3R3	560 1400 mcd	9.0 14.0 cd	Q65113A4696	_



Maximum Ratings Parameter	Symbol		Values
Operating Temperature	T <sub>op</sub>	min. max.	-40 °C 125 °C
Storage Temperature	$T_{stg}$	min. max.	-40 °C 125 °C
Junction Temperature 2)	T <sub>i</sub>	max.	135 °C
Junction Temperature for short time applications*	T <sub>i</sub>	max.	150 °C
Forward current T <sub>s</sub> = 25 °C	I <sub>F</sub>	min. max.	5 mA 200 mA
Forward current pulsed $t \le 10 \ \mu s; D \le 0.005 ; T_s = 25 \ ^{\circ}C$	F pulse	max.	1000 mA
Reverse voltage <sup>3)</sup> T <sub>s</sub> = 25 °C	$V_R$	max.	12 V
ESD withstand voltage acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 2)	$V_{ESD}$		2 kV

<sup>\*</sup> The median lifetime (L70/B50) for Tj = 150°C is 100h.



### **Characteristics**

 $I_F = 140 \text{ mA}; T_S = 25 \text{ }^{\circ}\text{C}$ 

Parameter	Symbol		Values
Peak Wavelength	$oldsymbol{\lambda}_{peak}$	typ.	624 nm
Dominant Wavelength 4)	$\lambda_{\sf dom}$	min.	612 nm
I <sub>F</sub> = 140 mA		typ.	617 nm
		max.	624 nm
Spectral Bandwidth at 50% I <sub>rel,max</sub>	Δλ	typ.	18 nm
Viewing angle at 50% $\rm I_{_{ m V}}$	2φ	typ.	120 °
Forward Voltage 5)	$V_{F}$	min.	1.90 V
I <sub>F</sub> = 140 mA	·	typ.	2.25 V
		max.	2.50 V
Reverse current 3)	I <sub>R</sub>	max.	10 µA
V <sub>R</sub> = 12 V		typ.	0.01 µA
Real thermal resistance junction/solderpoint <sup>6)</sup>	R <sub>thJS real</sub>	typ.	38 K / W
	0.00.100	max.	50 K / W
Electrical thermal resistance junction/solderpoint <sup>6)</sup>	R <sub>thJS elec.</sub>	typ.	23 K / W
with efficiency $\eta_e$ = 39 %	1100 0100.	max.	31 K / W



# **Brightness Groups**

Group	Luminous Intensity <sup>1)</sup> I <sub>F</sub> = 10 mA	Luminous Intensity. 1) I <sub>F</sub> = 10 mA	Luminous Flux <sup>7)</sup> I <sub>F</sub> = 10 mA
	min.	max.	typ.
	l <sub>v</sub>	l <sub>v</sub>	$\Phi_{v}$
U2	560 mcd	710 mcd	1905 mlm
V1	710 mcd	900 mcd	2415 mlm
V2	900 mcd	1120 mcd	3030 mlm
AA	1120 mcd	1400 mcd	3780 mlm

# **Brightness Groups**

Group	Luminous Intensity <sup>1)</sup> I <sub>F</sub> = 140 mA min. I <sub>v</sub>	Luminous Intensity. 1)  I <sub>F</sub> = 140 mA  max. I <sub>v</sub>	Luminous Flux <sup>7)</sup> $I_F = 140 \text{ mA}$ typ. $\Phi_V$
7E	9.0 cd	10.0 cd	28.5 lm
8E	10.0 cd	11.2 cd	31.8 lm
5F	11.2 cd	12.5 cd	35.6 lm
6F	12.5 cd	14.0 cd	39.8 lm



# **Forward Voltage Groups**

Group Forward Voltage $^{5)}$ $I_F = 10 \text{ mA}$		Forward Voltage <sup>5)</sup> I <sub>F</sub> = 10 mA	
	min.	max.	
	$V_{F}$	$V_{F}$	
A3	1.60 V	1.75 V	
D3	1.75 V	1.90 V	

# **Forward Voltage Groups**

Group	Forward Voltage <sup>5)</sup> I <sub>F</sub> = 140 mA min. V <sub>F</sub>	Forward Voltage <sup>5)</sup> I <sub>F</sub> = 140 mA max. V <sub>F</sub>	
G3	1.90 V	2.05 V	
K3	2.05 V	2.20 V	
N3	2.20 V	2.35 V	
R3	2.35 V	2.50 V	



# **Wavelength Groups**

Group Dominant Wavelength 4)		Dominant Wavelength 4)	
$I_F = 10 \text{ mA}$		$I_F = 10 \text{ mA}$	
	min.	max.	
	$\lambda_{\sf dom}$	$\lambda_{\sf dom}$	
1	611 nm	624 nm	

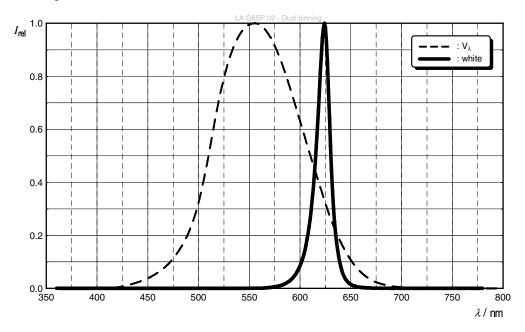
# **Wavelength Groups**

Group Dominant Wavelength $^{4)}$ $I_F = 140 \text{ mA}$ min.		Dominant Wavelength <sup>4)</sup> I <sub>F</sub> = 140 mA max.	
	$\lambda_{dom}$	$\lambda_{\sf dom}$	
2	612 nm	616 nm	
3	616 nm	620 nm	
4	620 nm	624 nm	



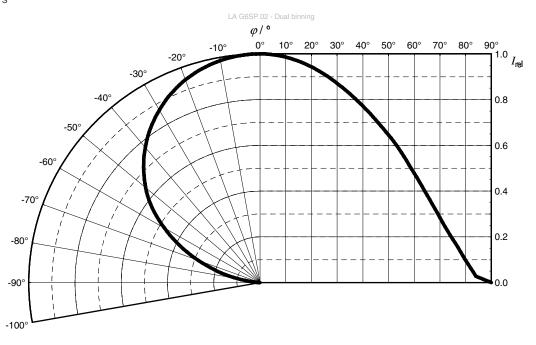
### Relative Spectral Emission 7)

 $I_{rel}$  = f ( $\lambda$ );  $I_{F}$  = 140 mA;  $T_{S}$  = 25 °C



#### Radiation Characteristics 7)

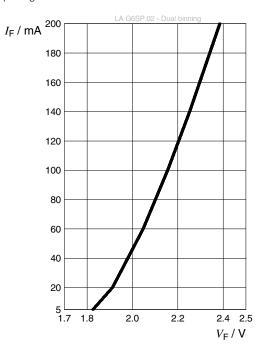
 $I_{rel} = f(\phi); T_S = 25 °C$ 





# Forward current 7)

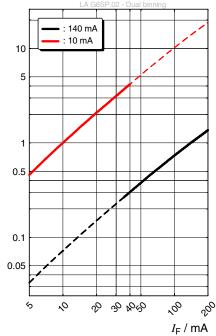
$$I_F = f(V_F); T_S = 25 \, ^{\circ}C$$



## Relative Luminous Intensity 7), 8)

$$I_{v}/I_{v}(I_{F \text{ group}}) = f(I_{F}); T_{S} = 25 \text{ }^{\circ}\text{C}$$

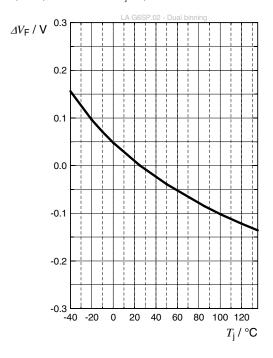






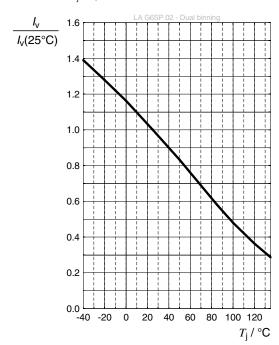
#### Forward Voltage 7)

$$\Delta V_{_F} = V_{_F} - V_{_F} (25 \ ^{\circ}C) = f(T_{_j}); \ I_{_F} = 140 \ mA$$



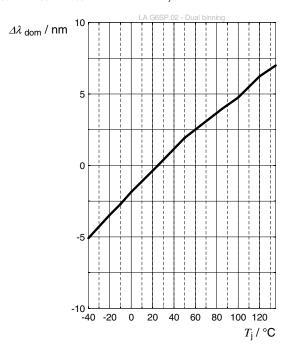
### Relative Luminous Intensity 7)

$$I_{v}/I_{v}(25 \text{ °C}) = f(T_{i}); I_{F} = 140 \text{ mA}$$



## **Dominant Wavelength** 7)

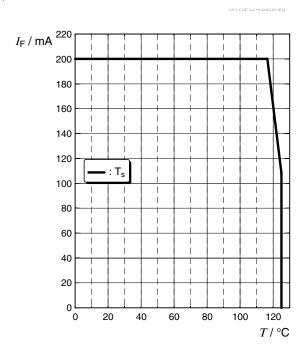
$$\Delta \lambda_{\text{dom}} = \lambda_{\text{dom}} - \lambda_{\text{dom}} (25 \ ^{\circ}\text{C}) = \text{f(T_j); I_F} = 140 \ \text{mA}$$





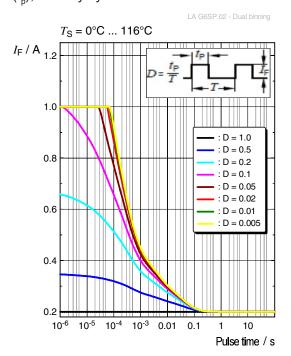
#### Max. Permissible Forward Current

 $I_{\scriptscriptstyle F} = f(T)$ 



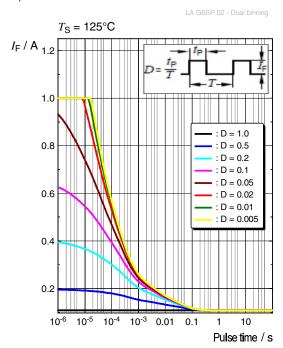
### Permissible Pulse Handling Capability

 $I_F = f(t_p)$ ; D: Duty cycle



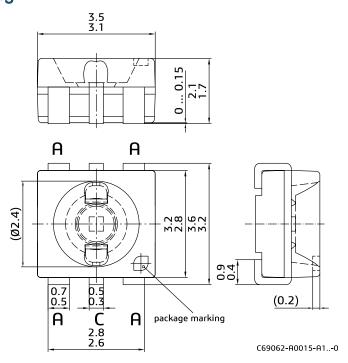
## Permissible Pulse Handling Capability

 $I_F = f(t_p)$ ; D: Duty cycle





## **Dimensional Drawing** 9)



#### **Further Information:**

**Approximate Weight:** 40.0 mg

Package marking: Cathode

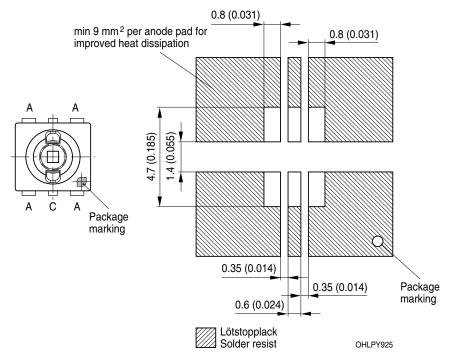
**Corrosion test:** Class: 3B

Test condition: 40°C / 90 % RH / 15 ppm H<sub>2</sub>S / 14 days (stricter than IEC

60068-2-43)



### Recommended Solder Pad 9)

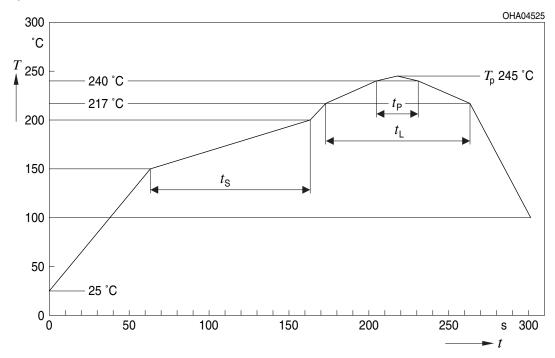


For superior solder joint connectivity results we recommend soldering under standard nitrogen atmosphere. Package not suitable for ultra sonic cleaning.



### **Reflow Soldering Profile**

Product complies to MSL Level 2 acc. to JEDEC J-STD-020E



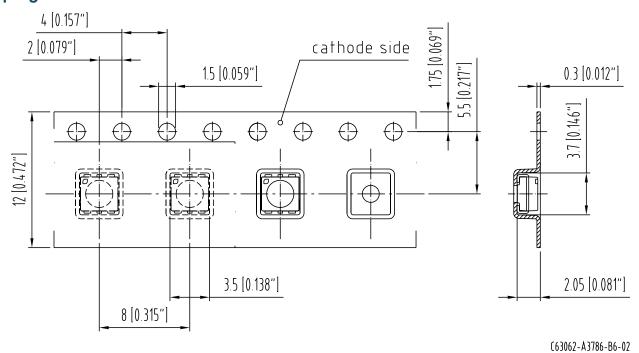
Profile Feature	Symbol Pb-Free (SnAgCu) Assembly		sembly	Unit	
		Minimum	Recommendation	Maximum	
Ramp-up rate to preheat*)			2	3	K/s
25 °C to 150 °C					
Time t <sub>s</sub>	$t_s$	60	100	120	S
$T_{Smin}$ to $T_{Smax}$					
Ramp-up rate to peak*)			2	3	K/s
$T_{Smax}$ to $T_{P}$					
Liquidus temperature	$T_L$		217		°C
Time above liquidus temperature	$t_{\scriptscriptstyle \! \! \! \! \! \! \! \! \! \! \! \! \! \! \! \! \! \! \!$		80	100	S
Peak temperature	T <sub>P</sub>		245	260	°C
Time within 5 °C of the specified peak temperature T <sub>p</sub> - 5 K	t <sub>P</sub>	10	20	30	S
Ramp-down rate* T <sub>p</sub> to 100 °C			3	6	K/s
Time 25 °C to T <sub>P</sub>				480	S

All temperatures refer to the center of the package, measured on the top of the component

<sup>\*</sup> slope calculation DT/Dt: Dt max. 5 s; fulfillment for the whole T-range

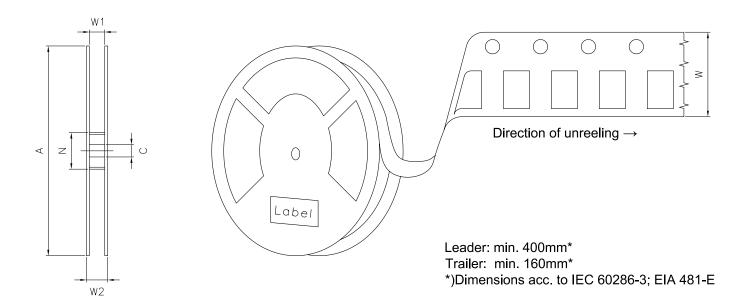


# Taping 9)





## Tape and Reel 10)

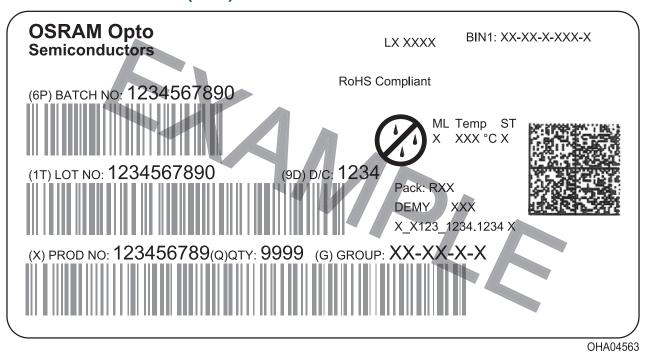


#### **Reel Dimensions**

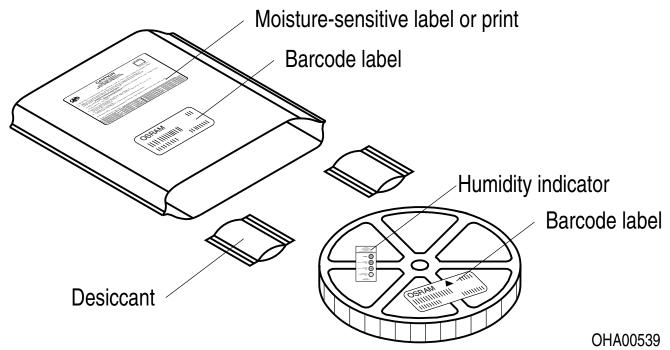
Α	W	$N_{\min}$	$W_1$	$W_{2  \text{max}}$	Pieces per PU
180 mm	12 + 0.3 / - 0.1 mm	60 mm	12.4 + 2 mm	18.4 mm	1000



#### **Barcode-Product-Label (BPL)**



## Dry Packing Process and Materials 9)



Moisture-sensitive product is packed in a dry bag containing desiccant and a humidity card according JEDEC-STD-033.



#### **Notes**

The evaluation of eye safety occurs according to the standard IEC 62471:2006 (photo biological safety of lamps and lamp systems). Within the risk grouping system of this IEC standard, the device specified in this data sheet fall into the class exempt group (exposure time 10000 s). Under real circumstances (for exposure time, conditions of the eye pupils, observation distance), it is assumed that no endangerment to the eye exists from these devices. As a matter of principle, however, it should be mentioned that intense light sources have a high secondary exposure potential due to their blinding effect. When looking at bright light sources (e.g. headlights), temporary reduction in visual acuity and afterimages can occur, leading to irritation, annoyance, visual impairment, and even accidents, depending on the situation.

Subcomponents of this device contain, in addition to other substances, metal filled materials including silver. Metal filled materials can be affected by environments that contain traces of aggressive substances. Therefore, we recommend that customers minimize device exposure to aggressive substances during storage, production, and use. Devices that showed visible discoloration when tested using the described tests above did show no performance deviations within failure limits during the stated test duration. Respective failure limits are described in the IEC60810.

For further application related information please visit www.osram-os.com/appnotes



#### Disclaimer

#### Attention please!

The information describes the type of component and shall not be considered as assured characteristics. Terms of delivery and rights to change design reserved. Due to technical requirements components may contain dangerous substances.

For information on the types in question please contact our Sales Organization.

If printed or downloaded, please find the latest version on our website.

#### **Packing**

Please use the recycling operators known to you. We can also help you – get in touch with your nearest sales office. By agreement we will take packing material back, if it is sorted. You must bear the costs of transport. For packing material that is returned to us unsorted or which we are not obliged to accept, we shall have to invoice you for any costs incurred.

#### Product and functional safety devices/applications or medical devices/applications

Our components are not developed, constructed or tested for the application as safety relevant component or for the application in medical devices.

Our products are not qualified at module and system level for such application.

In case buyer – or customer supplied by buyer – considers using our components in product safety devices/ applications or medical devices/applications, buyer and/or customer has to inform our local sales partner immediately and we and buyer and /or customer will analyze and coordinate the customer-specific request between us and buyer and/or customer.



#### Glossary

- Brightness: Brightness values are measured during a current pulse of typically 25 ms, with an internal reproducibility of ±8 % and an expanded uncertainty of ±11 % (acc. to GUM with a coverage factor of k = 3).
- Package discoloration: The LED chip exhibits excellent performance but slight package discoloration occurs at highest temperatures.
- 3) Reverse Operation: This product is intended to be operated applying a forward current within the specified range. Applying any continuous reverse bias or forward bias below the voltage range of light emission shall be avoided because it may cause migration which can change the electro-optical characteristics or damage the LED.
- Wavelength: The wavelength is measured at a current pulse of typically 25 ms, with an internal reproducibility of ±0.5 nm and an expanded uncertainty of ±1 nm (acc. to GUM with a coverage factor of k = 3).
- Forward Voltage: The forward voltage is measured during a current pulse of typically 8 ms, with an internal reproducibility of ±0.05 V and an expanded uncertainty of ±0.1 V (acc. to GUM with a coverage factor of k = 3).
- 6) **Thermal Resistance:** Rth max is based on statistic values  $(6\sigma)$ .
- Typical Values: Due to the special conditions of the manufacturing processes of semiconductor devices, the typical data or calculated correlations of technical parameters can only reflect statistical figures. These do not necessarily correspond to the actual parameters of each single product, which could differ from the typical data and calculated correlations or the typical characteristic line. If requested, e.g. because of technical improvements, these typ. data will be changed without any further notice.
- Characteristic curve: In the range where the line of the graph is broken, you must expect higher differences between single devices within one packing unit.
- Tolerance of Measure: Unless otherwise noted in drawing, tolerances are specified with ±0.1 and dimensions are specified in mm.
- Tape and Reel: All dimensions and tolerances are specified acc. IEC 60286-3 and specified in mm.



# **Revision History**

Version	Date	Change
1.0	2022-04-26	Initial Version
1.0	2022-04-26	Initial Version



EU RoHS and China RoHS compliant product 此产品符合欧盟 RoHS 指令的要求; 按照中国的相关法规和标准, 不含有毒有害物质或元素。

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